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**Takeuchi et al.**

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(54) **METHOD AND SYSTEM FOR ATTACHMENT OF A HEAT SINK TO A CIRCUIT BOARD**

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U.S. Appl. No. 13/943,556, filed Jul. 16, 2013, to Kevin M. Takeuchi,  
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(57) **ABSTRACT**

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A computer system including a heat sink including a peripheral portion and a middle portion, a circuit board, a first controller configured to be secured to the circuit board, one or more attachment devices configured to secure the heat sink to the circuit board at the peripheral portion of the heat sink, and a standoff component. The standoff component includes a first threaded section configured to secure the standoff component to the circuit board, and a second threaded section configured to secure the standoff component to the heat sink at the middle portion of the heat sink. The one or more attachment devices and the standoff component are configured to secure the heat sink to the circuit board and allow the heat sink to have thermal contact with the first controller.

(52) **U.S. Cl.**  
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See application file for complete search history.

**5 Claims, 10 Drawing Sheets**

